



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT:001

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|-------------------------------------|-----------------------------------|-----------|--------------------------------|
| PCB VIEWED FROM BOTTOM SIDE | BOARD #: TIDA-01323 | REV: E1.0 | SUN REV: Not In VersionControl |
| | TID #: 01323 | | |
| PLOT NAME = Bottom Assembly Drawing | GENERATED : 10/19/2017 2:11:55 PM | | TEXAS INSTRUMENTS |

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